

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6955834

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT	
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CONVEYING PARTY DATA previously recorded on Reel 054494 Frame 0894. Assignor(s) hereby confirms the CORRECT CONVEYING PARTY DATA AS HEADWAY TECHONOLOGIES, INC..	
CONVEYING PARTY DATA		
	Name	Execution Date
	HEADWAY TECHNOLOGIES, INC.	02/04/2019
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	8, LI-HSIN RD. 6	
Internal Address:	HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17107409
CORRESPONDENCE DATA		
Fax Number:	(214)200-0853	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Email:	ipdocketing@haynesboone.com	
Correspondent Name:	HAYNES AND BOONE, LLP (24061) IP SECTION	
Address Line 1:	2323 VICTORY AVENUE	
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Address Line 4:	DALLAS, TEXAS 75219	
ATTORNEY DOCKET NUMBER:	P2900129/24061.3906US02	
NAME OF SUBMITTER:	MARCY OGADO	
SIGNATURE:	/Marcy Ogado/	
DATE SIGNED:	10/06/2021	
Total Attachments: 20		
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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1

Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HEADWAY TECHNOLOGIES, INC.	02/04/2019
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Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17107409
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: HAYNES AND BOONE, LLP (24061) IP SECTION
Address Line 1: 2323 VICTORY AVENUE
Address Line 2: SUITE 700
Address Line 4: DALLAS, TEXAS 75219

**ATTORNEY DOCKET
NUMBER:**

P2900129/24061.3906US02

NAME OF SUBMITTER:

MARCY OGADO

Signature:

/Marcy Ogado/

Date:

11/30/2020

Total Attachments: 18

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RECEIPT INFORMATION

EPAS ID: PAT6423623
Receipt Date: 11/30/2020

[Return to home page](#)

| [HOME](#) | [INDEX](#) | [SEARCH](#) | [eBUSINESS](#) | [CONTACT US](#) | [PRIVACY STATEMENT](#)

EXHIBIT B
Patent Assignment

Headway Technologies, Inc., a California Corporation, with an office at 682 South Hillview Drive, Milpitas, CA 95035 ("Assignor") is the owner of the patents and patent applications listed in Schedule 1 hereto (collectively the "Listed Patents"); and

Taiwan Semiconductor Manufacturing Company, Ltd, a Republic of China (Taiwan) company that maintains its principal place of business at No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan, R.O.C. ("Assignee"), desires to acquire all right, title and interest in the Listed Patents and the other patents and related rights described below.

For good and valuable consideration, the receipt of which is hereby acknowledged, Assignor does hereby sell, assign, transfer and convey to Assignee and its successors and assigns all right, title and interest that may exist today and in the future to any and all:

- (1) Listed Patents;
- (2) patents and patent applications to which any of the Listed Patents directly or indirectly claims priority anywhere in the world;
- (3) reissues, reexaminations, extensions, continuations, continuations-in-part (except for claims in future continuations-in-part that claim new matter), continuing prosecution applications and divisions of any of the items covered by (1) or (2) above;
- (4) foreign counterparts to any of the items covered by (1), (2) or (3) above, including without limitation utility models, inventors' certificates, industrial design protection and any other form of governmental grants or issuances for the protection of inventions, designs or discoveries;
- (5) inventions, invention disclosures, designs and discoveries described, disclosed or claimed in the items covered by (1) through (4) above;
- (6) patents that issue from any of the items covered by (1) through (5) above;
- (7) claims, causes of action and enforcement rights of any kind, whether currently pending, filed or otherwise, and whether known or unknown, under or arising from any of the items covered by (1) through (6) above, including without limitation all rights to pursue and collect damages, costs, injunctive relief and other remedies for past, current or future infringement thereof and including without limitation rights afforded under 35 U.S.C. § 154(d);
- (8) royalties, income and other payments due as of the date hereof or hereafter under or arising from any of the items covered by (1) through (7) above; and
- (9) rights to apply for, file, register, maintain, extend and renew in any or all countries of the world patents, certificates of invention, utility models, industrial design protection, design patent protection and other governmental grants or issuances of any kind related to any of the items covered by (1) through (8) above.

Assignor shall execute and deliver any instruments, and do and perform any other acts and things as may be reasonably necessary or desirable for effecting and evidencing the assignments contemplated hereby,

including without limitation the execution, acknowledgment and recordation of any instruments.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks and any other patent office to issue any and all patents, utility models or other governmental grants or issuances pertaining to any of the items assigned hereunder in the name of Assignee.

The assignments and rights pursuant hereto will inure to the benefit of Assignee and its successors, assigns and other legal representatives and is binding upon Assignor and its successors, assigns, heirs and legal representatives.

Assignor, by its duly authorized representative, has executed this assignment on the date set forth below.

DATE: Feb 4, 2019

Headway Technologies, Inc.

By: WENJIE CHEN
Printed/Typed Name
Title: President & CEO
Signature: Wenjie Chen

A notary public or other officer completing this certificate verifies only the identity of the individual who signed the document to which this certificate is attached, and not the truthfulness, accuracy, or validity of that document.

State of California
County of Santa Clara

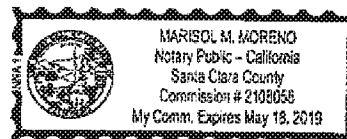
On Feb. 4, 2019 before me, Marisol M. Moreno, Notary Public, personally appeared Wenjie Chen, who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature of Notary Public

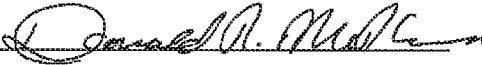
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ACCEPTED:

DATE: March 11, 2019

Taiwan Semiconductor Manufacturing
Company, Ltd

By: 

Name: Donald R. McKenna
Printed/Typed Name

Title: Director

Schedule 1 to Patent Assignment

U.S.

Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	IBM	Renesas	Remark
US7321507	Reference Cell Scheme for MRAM	Yang	11284299	11/21/2005	1/22/2008	○	○	
US7499314	A Reference Cell Scheme for MRAM	Yang	12002161	12/14/2007	3/3/2009	○	○	
US7480172	A Novel Programming Scheme for Segmented Word Line MRAM Array	Shi	11339189	1/25/2006	1/20/2009	○	○	
US7265404	A Novel Bottom Conductor Lead Structure /Method For Fabricating High Performance MTJ for MRAM Applic	Cao	11215276	8/30/2005	9/4/2007	○	○	
US7358100	Improved Bottom Conductor for Integrated MRAM	Cao	11691923	8/14/2007	4/15/2008	○	○	
US7880249	Spacer Structure In MRAM Cell And Method Of Fabricating The Same	Yuan	11290763	11/30/2005	2/1/2011	○	○	
US8422276	Space Structure in MRAM Cell and Method of Its Fabrication	Yuan	12930955	1/20/2011	4/16/2013	○	○	
US7695548	MRAM with Super-paramagnetic sensing layer	Wang	11200380	8/9/2005	4/13/2010	○	○	
US8039885	MRAM with Storage Layer and Super Paramagnetic Sensing Layer	Wang	12661345	3/16/2010	10/18/2011	○	○	
US8062908	MRAM with Storage Layer and Super Paramagnetic Sensing Layer	Wang	12661365	3/16/2010	11/22/2011	○	○	
US8178363	MRAM with Storage Layer and Super-Paramagnetic Sensing Layer	Wang	13373127	11/4/2011	5/15/2012	○	○	
US7362644	A Configurable MRAM	Yang	11313019	12/20/2005	4/22/2008	○	○	
US7345911	Multi-Bit Thermal Assisted Integrated Storage Layer MRAM Design	Min	11353326	2/14/2006	3/18/2008	○	○	
US7588945	Multi-State Thermally Assisted Storage	Min	12012576	2/4/2008	9/15/2009	○	○	
US7479394	A Novel Oxidation Structure/Method To Form MgO/NiFe(free layer)-MTJ for high performance MRAM appli	Hong	11317388	12/22/2005	1/20/2009	○	○	
US8674486	Magnetic Random Access Memory with Selective Toggle Memory Cell	Geu	12151224	5/5/2008	3/18/2014	○	○	
US7838436	Bottom Electrode For MRAM Device And Method To Fabricate It	Hong	11528877	9/29/2006	11/23/2010	○	○	
US8273666	Process to Fabricate Bottom Electrode for MRAM Device	Xiao	12927615	11/19/2010	9/25/2012	○	○	
US8969982	Bottom Electrode for MRAM Device	Xiao	12927670	11/19/2010	3/3/2015	○	○	
US7458029	Planar Flux Concentrator For MRAM Devices	Guo	11476495	6/28/2006	11/25/2008	○	○	
US7582942	Planar Flux Concentrator for MRAM Devices	Guo	12290410	10/30/2008	9/1/2009	○	○	
US7672093	Hafnium Doped Cap and Free Layer for MRAM Device	Hong	11582244	10/17/2006	3/2/2010	○	○	
US7508042	Spin Transfer MRAM Device With Magnetic Biasing	Guo	11644132	12/22/2006	3/24/2009	○	○	
US7715224	MRAM with Enhanced Programming Margin	Min	11787330	4/16/2007	5/11/2010	○	○	
US7885064	MRAM With Cross-Tie Magnetization	Min	12159241	4/25/2008	2/8/2011	○	○	
US7609543	Method and Implementation Of Stress Test for MRAM	Yang	11904434	9/27/2007	10/27/2009	○	○	
US7480173	Spin Transfer MRAM Device With Novel Magnetic Free Layer	Guo	11717347	3/13/2007	1/20/2009	○	○	
US8058697	Spin Transfer MRAM Device With Novel Magnetic Synthetic Free Layer	Guo	11725491	3/26/2007	11/15/2011	○	○	
US8268641	Spin Transfer MRAM Device with Novel Magnetic Synthetic Free Layer	Guo	13373173	11/7/2011	9/18/2012	○	○	
US7852662	Spin Torque Switching MRAM, SpinRAM, Array	Yang	11789324	4/24/2007	12/14/2010	○	○	
US7508700	Method Of Magnetic Tunneling Layer Pattern Layout For MRAM	Zhong	11724435	3/15/2007	3/24/2009	○	○	
US8497558	MRAM With Means of Controlling Magnetic Anisotropy	Min	11973751	10/10/2007	7/30/2013	○	○	
US7663131	A Novel SyAF Structure To Fabricate Mbit MTJ MRAM	Hong	11715728	3/8/2007	2/16/2010	○	○	
US8865321	Spin Transfer MRAM Device with Reduced Coefficient of MTJ Resistance Variation	Guo	11881627	7/22/2016	1/9/2018	○	○	
US7750421	A High Performance MTJ Element for STT-RAM And Method For Making the Same	Hong	11880583	7/23/2007	7/8/2010	○	○	
US8435437	A High Performance MTJ Element for STT-RAM and Method for Making the Same	Hong	12803191	6/21/2010	5/7/2013	○	○	
US8059898	A High Performance MTJ Element for STT-RAM and Method for Making the Same	Hong	12803189	6/21/2010	11/15/2011	○	○	
US8080432	A High Performance MTJ Element STT-RAM and Method for Making the Same	Hong	12803190	6/21/2010	12/20/2011	○	○	
US8133745	Method Of Magnetic Tunneling Layer Processes For Spin-Transfer Torque MRAM Devices	Zhong	11975045	10/17/2007	3/13/2012	○	○	
US7938027	Method Of MRAM Fabrication With Zero Electrical Shorting	Xiao	12006889	1/7/2008	5/3/2011	○	○	
US7577021	Spin Transfer MRAM Device With Separated CPP Assisted Writing	Guo	11966375	11/21/2007	6/18/2009	○	○	
US7755933	Spin Transfer MRAM Device with Separated CPP Assisted Writing	Guo	12462453	8/4/2009	7/13/2010	○	○	
US7780544	Spin Transfer MRAM Device with Separated CPP Assisted Writing	Guo	12462434	8/4/2009	7/20/2010	○	○	

US7764536	Spin Transfer MRAM Device with Separated CPP Assisted Writing	Guo	12462462	8/4/2009	7/27/2010	○	○	
US8334213	Bottom Electrode Etching Process in MRAM Cell	Mao	12455757	6/5/2009	12/18/2012	○	○	
US8372661	A High Performance MTJ Element for Conventional MRAM And For STT-RAM And Method For Making The Same	Hong	11981127	10/31/2007	2/12/2013	○	○	
US8749003	A High Performance MTJ Element for Conventional MRAM and for STT-RAM and a Method for Making the Same	Hong	13764357	2/11/2013	6/10/2014	○	○	
US8057925	A Low Switching Current Dual Spin Filter (DSF) Element for STT-RAM and Method for Making The Same	Hong	12079445	3/27/2008	11/15/2011	○	○	
US8404367	Low Switching Current Dual Spin Filter (DSF) Element for STT-RAM and a Method for Making the Same	Hong	13317484	10/19/2011	3/28/2013			
US8726491	Method of Forming a Spin-Transfer Torque Random Access Memory (STT-RAM) Device	Hong	13373128	11/4/2011	5/20/2014	○	○	
US7948044	A Low Switching Current MTJ Element For Ultra-High STT-RAM and Method For Making The Same	Hong	12082155	4/9/2008	5/24/2011	○	○	
US7752661	Boosted Gate Voltage Programming For Spin-RAM Array	Hsu	12313487	11/20/2008	8/24/2010	○	○	
US8248841	Boosted Gate Voltage Programming for Spin-Torque MRAM Array	Yang	12806094	8/5/2010	8/21/2012	○	○	
US8138561	Structure and Method To Fabricate High Performance MTJ Devices For Spin-Transfer Torque (STT) - RAM	Hong	12284088	9/18/2008	3/20/2012	○	○	
US7929370	A Novel Spin Momentum Transfer MRAM Design	Min	12313708	11/24/2008	4/19/2011	○	○	
US7957163	Single Bit Line SMT MRAM Array Architecture and the Programming Method	Yang	12387537	5/4/2009	8/7/2011	○	○	
US7804706	Bottom Electrode Mask Design For Ultra-Thin Interlayer Dielectric Approach in MRAM Devices Fabricati	Zhong	12313117	11/17/2008	9/26/2010	○	○	
US7994597	A Novel MRAM Design With Coupling Valve Switching Mechanism	Min	12381667	3/13/2009	8/9/2011	○	○	
US7884433	Method for High Density Spin-Transfer Torque MRAM Process	Zhong	12290495	10/31/2008	2/8/2011	○	○	
US8324693	High Density Spin-Transfer Torque MRAM Process	Zhong	12830333	1/4/2011	12/4/2012	○	○	
US8183061	A High Density Spin-Transfer Torque MRAM Process	Zhong	12931648	2/7/2011	5/22/2012	○	○	
US8018758	Gate Drive Voltage Boost Schemes For Memory Array	Yang	12459655	7/6/2009	9/13/2011	○	○	
US7985572	Magnetic Memory Capable Of Minimizing Gate Voltage Stress In Unselected Memory Cells	Yang	12583255	8/17/2009	7/26/2011	○	○	
US9170879	Scrubbing the Accumulated Read Error in A Memory System	Yang	12458923	6/24/2008	10/27/2015	○	○	
US7808027	A Novel Free Layer/Capping Layer For High Performance MRAM MTJ	Hong	12319971	1/14/2009	10/6/2010	○	○	
US8609262	STT-RAM with A Magnetic Tunnel Junction Written in Thermally Assisted Method	Hong	12460412	7/17/2009	12/17/2013	○	○	
US9331271	Structure and Method to Fabricate High Performance MTJ Devices for Spin-Transfer Torque (STT)-RAM Application	Hong	14098604	12/8/2013	5/3/2016	○	○	
US7863060	Method of Double Patterning and Etching Magnetic Tunnel Junction Structures for Spin-Transfer Torque	Belen	12383298	3/23/2009	1/4/2011	○	○	
US8437181	Shared Bit Line Array With Switch Transistors Between the Bit Lines	Yang	12803523	8/29/2010	5/7/2013	○	○	
US8565014	Shared Bit Line SMT MRAM Array with Shunting Transistors Between the Bit Lines	Yang	13887287	5/4/2013	10/22/2013	○	○	
US8576618	Shared Bit Line SMT MRAM Array with Shunting Transistors Between the Bit Lines	Yang	13887288	5/4/2013	11/5/2013	○	○	
US8570793	Shared Bit Line SMT MRAM Array with Shunting Transistors Between the Bit Lines	Yang	13887289	5/4/2013	10/29/2013	○	○	
US8654577	Shared Bit Line SMT MRAM Array with Shunting Transistors Between the Bit Lines	Yang	13887291	5/4/2013	2/18/2014	○	○	
US7919407	Method of High Density Field Inducted MRAM Process	Tom	12590845	11/17/2009	4/5/2011	○	○	
US9343463	Method of High Density Memory Fabrication	Tom	12588900	9/29/2008	5/17/2016	○	○	
US8274919	Read Disturb Free SMT Reference Cell Scheme II	Yang	12656226	2/4/2010	8/25/2012	○	○	
US8138562	A Novel Bit Line Preparation Method in MRAM Fabrication	Mao	12559193	10/20/2009	3/20/2012	○	○	

US8722543	Composite Hard Mask With Upper Sacrificial Dielectric Layer for the Patterning and Etching of Nanometer Size MRAM Devices	Belen	12804840	7/30/2010	5/13/2014	○	○	
US8422287	A pulse field assisted spin momentum transfer MRAM design	Min	12807611	9/9/2010	4/16/2013	○	○	
US8133909	Method to Fabricate Thin Metal Via Interconnects on Copper Wires in MARM Devices	Mao	12806361	6/11/2010	3/13/2012	○	○	
US8605520	Replaceable, Predictable-Tracking Reference Lines	Pu	12824184	9/22/2010	12/10/2013	○	○	
US8493357	Reference Cell Architectures for Small Memory Array Block Activation	Sunaga	12925492	10/22/2010	7/16/2013	○		
US8217684	Fast and Accurate Current Driver with Zero Standby Current and Features for Boost and Temperature Compensation for MRAM Write	Yuh	12925004	10/12/2010	7/10/2012	○		
US8785036	Improved Magnetic Tunnel Junction for MRAM Applications	Cao	12930877	1/19/2011	7/22/2014	○		
US9224940	Magnetic Tunnel Junction for MRAM Applications	Cao	14315436	6/26/2014	12/29/2015	○		
US9455400	Magnetic Tunnel Junction for MRAM Applications	Cao	14879949	12/28/2015	9/27/2016			
US8693273	Averaging for MRAM Sense Amplifiers Method and Apparatus for Scrubbing	Yuh	13345116	1/5/2012	4/9/2014			
US8775865	Accumulated Disturb Data Errors in Array of SMT MRAM Mem Cells Inc Rewriting Ref Bits	Yang	13136292	7/28/2011	7/8/2014			
US8492169	Improved Magnetic Tunnel Junction for MRAM Applications	Cao	13136929	6/15/2011	7/23/2013			
US8738004	Magnetic Tunnel Junction for MRAM Applications	Wei	13841741	7/16/2013	8/27/2014			
US8900884	MTJ Element for STT MRAM	Wilold	13525502	6/18/2012	12/2/2014			
US8921961	Storage Element for STT MRAM Applications	Kula	13617432	9/14/2012	12/30/2014			
US8991503	STT-MRAM Reference Layer Having Substantially Reduced Stray Field and Consisting of a Single Magnetic Domain	Beach	13421863	3/16/2012	3/17/2015			
US8968895	MRAM Cell With Flat Topography and Controlled Bit Line to Free Layer Distance and Method of Manufact	Han	10732013	12/10/2003	11/29/2005	○	○	
US7335960	MRAM Cell with Flat Topography and Controlled Bit Line to Free Layer Distance and Method of Manufact	Han	11178262	7/12/2005	2/26/2008	○	○	
US6974708	Oxidation Structure/Method to Fabricate a High-Performance Magnetic Tunneling Junction MRAM	Hong	10820391	4/8/2004	12/13/2005	○	○	
US7045841	Oxidation Structure/Method to Fabricate a High-Performance Magnetic Tunneling Junction MRAM	Hong	11268352	11/7/2005	5/16/2006	○	○	
US6979586	Magnetic Random Access Memory Array with Coupled Soft Adjacent Magnetic Layer	Guo	10872916	6/21/2004	12/27/2005	○	○	
US7085183	Adaptive Algorithm for MRAM Manufacturing	Yang	10889911	7/13/2004	8/1/2006	○	○	
US7045368	MRAM Cell Structure and Method of Fabrication	Hong	10849311	6/19/2004	5/16/2006	○	○	
US7476919	MRAM Cell Structure and Method of Fabrication	Hong	11418910	5/5/2006	1/13/2009	○	○	
US7811912	A Novel Underlayer For High Performance Magnetic Tunneling Junction MRAM	Hong	10881445	6/30/2004	11/3/2009	○	○	
US7999360	A Novel Underlayer for High Performance Magnetic Tunneling Junction MRAM	Hong	12589466	10/23/2009	6/16/2011	○	○	
US8673854	A Novel Underlayer for High Performance Magnetic Tunneling Junction MRAM	Hong	12589465	10/23/2009	3/16/2014	○	○	
US7241632	Method of Fabricating MRAM Cell Structure Containing Sidewall Spacers	Yang	11106320	4/14/2005	7/10/2007	○	○	
US7544983	MTJ read head with sidewall spacers	Yang	11825032	7/3/2007	6/9/2008	○	○	
US7978505	Heat Assisted Switching and Separated Read-Write MRAM	Zhou	12322107	1/29/2009	7/12/2011	○	○	
US8184411	MTJ incorporating CoFe/Ni multilayer film with perpendicular anisotropy for MRAM application	Zhang	12589614	10/26/2009	5/22/2012	○	○	
US8456883	Method of Spin Torque MRAM Process Integration	Liu	13482157	5/29/2012	6/4/2013			
US8660158	Minimal Thickness SAF Structure with Perpendicular Magnetic Anisotropy for STT-MRAM	Beach	13809780	9/11/2012	10/14/2014			
	Minimal Thickness Synthetic Antiferromagnetic (SAF) Structure with Perpendicular Magnetic Anisotropy for STT-MRAM	Beach	14499507	9/18/2014				
US8772051	Fabrication Method for Embedded Magnetic Memory	Zhong	13766890	2/14/2013	7/8/2014			

US6917536	Adaptive Reference Scheme for Magnetic Memory Applications	Jan	13560176	10/25/2012	12/23/2014			
US9343132	MRAM Write Pulses to Dissipate Intermediate State Domains	Lee	13899923	5/22/2013	5/17/2016			
US9747665	Improved Adaptive Reference Scheme for Magnetic Memory Applications	Jan	14980050	12/28/2015	8/29/2017			
	Improved Adaptive Reference Scheme for Magnetic Memory Applications	Jan	15886448	8/25/2017				
US9805816	Implementation of One Time Programmable Memory using a MRAM Stack Design	Jan	15078182	3/23/2016	10/31/2017			
US8780299	Seed Layer for Improving the Thermal Budget of the PMA Layer for Embedded MRAM Applications	Zhu	14949232	11/23/2015	10/3/2017			
	Seed Layer for Improving the Thermal Budget of the PMA Layer for Embedded MRAM Applications	Zhu	15707373	9/15/2017				
	A Writing Scheme to Reduce Back Hopping for STT-MRAM	Liu	15616116	6/7/2017				
US996529	MgO Insertion in Free Layer for Magnetic Memory Applications	Iwata	15/461779	3/17/2017	5/6/2018			
	MgO Insertion in Free Layer for Magnetic Memory Applications	Iwata	15/972284	5/7/2018				
US9871195	Spacer Assisted Ion Beam Etching of Spin Torque Magnetic Random Access Memory	Yang	15/465644	3/22/2017	1/16/2018			
	STT-MRAM Heat Sink and Magnetic Shield Structure Design for More Robust Read/Write Performance	Zhong	15857782	12/29/2017				
				6/29/2018				Remark, it is #197
	Initialization Process for Magnetic Random Access memory	Lee	15818148	11/20/2017				
	Self-Adaptive Halogen Treatment to Improve Photoresist pattern and MRAM Device uniformity	Yang	15885240	8/24/2017				
	High Thermal Stability by Doping of Oxide Capping Layer for Spin Torque Transfer (STT) Magnetic Random Access Memory	Jan	15728818	10/10/2017				
US10134982	Free Layer Sidewall Oxidation and Spacer Assisted Magnetic Tunnel Junction (MTJ) Etch for High Performance Magnetoresistive Random Access Memory (MRAM) Devices	Yang	15789150	10/20/2017	11/20/2018			
	Nitride Capping Layer for Spin Torque Transfer (STT)-Magnetoresistive Random Access Memory (MRAM)	Iwata	15881035	1/25/2018				
	CMP Stop Layer and Sacrifice Layer for High-Yield Small Size MRAM Devices	Yang	15891767	2/8/2018				
	Multiply Spin-Coated Ultra-Thick Hybrid Hard Mask for Sub 60nm MRAM Devices	Yang	15899086	2/19/2018				
	Fabrication of Large Height Top Metal Electrode for Sub 60nm MRAM Devices	Yang	15902415	2/22/2018				
	Metal/Dielectric/Metal Hybrid to Define Ultra-large Height Top Electrode for Sub 60nm MRAM Devices	Yang	15902381	2/22/2018				
	Novel Free Layer Structure of Magnetoresistive Memory (MRAM) for Metal Mo or W Capping Layer	Fukuzawa	15/933479	3/23/2018				
	Ion Beam Etching Fabricated Sub 30nm Vias to Reduce Conductive Material Re-Deposition for Sub 60nm MRAM Devices	Yang	16/947512	4/6/2018				
	Highly Selective Ion Beam Etch Hard Mask for Sub 60nm MRAM Devices	Yang	15/951873	4/12/2018				
	Highly Physical Ion Resistive Spacer to Define Chemical Damage Free Sub 60nm MRAM Devices	Yang	15/988244	5/22/2018				
	Sub 60nm Etchless MRAM Devices by Ion Beam Etching Fabricated T-shaped Bottom Electrode	Yang	16/008529	8/14/2018				
	Under-cut Via Electrode for Sub 60nm Etchless MRAM Devices by Decoupling the Via Etch Process	Yang	16/008550	6/14/2018				
US7122386	Pad/DD Structure	Tong	11231674	9/21/2005	10/17/2006	○	○	
US9450119	Magnetic Tunnel Junction Patterning Using Ta/TaN as Hard Mask	Tong	11378555	3/17/2006	5/26/2013	○	○	
US7528457	A Novel Method To Form Non-magnetic NiFeMg Cap for the NiFe(free)-MTJ Stack to Enhance dR/R	Hong	11404446	4/14/2006	5/5/2009	○	○	
US7595520	Paramagnetic-NiFeHf Capping Layer Is Deposited By Co-Sputtering of NiFe and Hf	Hong	11496691	7/31/2006	9/29/2009	○	○	
US8378330	A Novel Capping Layer for a Magnetic Tunnel Junction Device to Enhance dR/R and a Method of Making	Hong	12584190	9/1/2009	2/19/2013	○	○	

US8176622	A Process For Manufacturing A Magnetic Tunnel Junction (MTJ) Device	Homg	12857775	1/27/2010	5/15/2012	○	○	
US7598579	A Novel Magnetic Tunnel Junction (MTJ) To Reduce Spin Transfer Magnetization Switching Current	Homg	11899875	1/30/2007	10/6/2009	○	○	
US8269292	A Novel Magnetic Tunnel Junction (MTJ) To Reduce Spin Transfer Magnetization Switching Current	Homg	12584946	9/15/2009	9/18/2012	○	○	
US8456893	A Novel Magnetic Tunnel Junction (MTJ) To Reduce Spin Transfer Magnetization Switching Current	Homg	12584971	9/15/2009	6/4/2013	○	○	
US7695551	Composite Hard Mask For the Patterning/Etching Of Nanometer-size Magnetic Multilayer-based device	Xiao	11901999	9/20/2007	4/13/2010	○	○	
US8105948	Method Of Exposing Magnetic Tunnel Junction Structure Using Chemical Mechanical Polishing	Zhong	12070286	2/14/2008	1/31/2012	○	○	
US8169816	Design and Fabrication Methods of Partial Cladded Write Line to Enhance Write Margin for Magnetic Ra	Min	12584952	9/15/2009	5/1/2012	○	○	
US8470462	Structure/Method for Enhancing Interfacial Perpendicular Anisotropy in CoFe(B)/MgO/CoFeB Magnetic Tunnel Junction	Homg	12927939	11/30/2010	6/25/2013	○		
US9159908	Composite magnetic free layer within magnetic tunnel junction for MRAM application	Cao	13066222	5/5/2011	10/13/2015	○		
US8541855	Co/Ni Multilayers with Improved Out-of-plane Anisotropy for Magnetic Device Applications	Jan	13068398	5/10/2011	9/24/2013	○		
US8508006	Co/Ni Multilayers with Improved Out-of-plane Anisotropy for Magnetic Device Applications	Jan	13561201	7/30/2012	5/13/2013			
US9373780	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	13955035	7/31/2013	6/21/2016	○		
US8695281	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	13955039	7/31/2013	4/15/2014	○		
US8987849	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14244943	4/4/2014	3/24/2015	○		
US8875323	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14032593	9/20/2013	11/4/2014	○		
US9373777	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14529242	10/31/2014	6/21/2016	○		
US9475733	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14529246	10/31/2014	10/25/2016	○		
US9373775	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14529251	10/31/2014	6/21/2016	○		
US9391265	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14529254	10/31/2014	7/12/2016	○		
US8987847	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14244937	4/4/2014	3/24/2015	○		
US9067049	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14244940	4/4/2014	3/24/2015	○		
US8962348	Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	14032599	9/20/2013	2/24/2015	○		
US9067044	Magnetic element with improved out-of-plane anisotropy for spintronics applications	Jan	12931866	2/11/2011	4/14/2015	○		
US8582927	Multilayers having reduced perpendicular demagnetizing field using moment dilution for spintronics applications	Jan	13068172	5/4/2011	11/26/2013	○		
US9048411	Multilayers Having Reduced Perpendicular Demagnetizing Field Using Moment Dilution for Spintronic Application	Jan	14047130	10/7/2013	6/2/2015	○		
US8823118	Spin Torque transfer MTJ fabricated with a composite tunneling barrier layer	Homg	13344292	1/5/2012	9/2/2014			
US8871365	High thermal stability reference structure with out-of plane anisotropy for Magnetic Device	Wang	13406972	2/28/2012	10/26/2014			
US9472752	High Thermal Stability Reference Structure with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	14493416	9/23/2014	10/16/2016			

US9466789	High Thermal Stability Reference Structure with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	14511273	10/10/2014	10/11/2016			
	Reduction of Capping Layer Resistance Area Product for Magnetic Device Applications	Jan	13441158	4/8/2012				
US9946934	High Thermal Stability Free Layer with High Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	13409456	3/1/2012	2/3/2015			
US9952760	High Thermal Stability Free Layer Structure with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	13448557	4/17/2012	10/7/2014			
US9748197	Reverse Partial Etching Scheme for Magnetic Device Applications	Wang	13419507	3/14/2012	6/10/2014			
	Improve MTJ CD Variation by HM Trimming	Shen	15/988183	5/22/2018				
US9929958	Method to Make Small Isolated Features with Pseudo-Planarization for TMR and MRAM	Han	10719723	11/21/2003	8/16/2005	○	○	
US9524511	Novel Method to Connect a Magnetic Device to CMOS Transistor	Zhong	13571675	8/10/2012	9/3/2013			
	Multi-Layer Structure for Reducing Film Roughness in Magnetic Devices	Zhu	15589755	5/19/2017				
US9860177	Method to Minimize MTJ Sidewall Damage and Bottom Electrode Redeposition using ISE Trimming	Annapragada	14/548378	9/9/2015	5/23/2017			
	Perpendicularly Magnetized Ferromagnetic Layers having an Oxide Interface Allowing for Improved Control of the Oxidation	Thomas	15/196807	6/29/2016				
US9973385	Seed Layer for Growth of <111> Magnetic Materials	Liu	15/079469	3/24/2016	6/8/2017			
US9880473	New Surface Treatment Method for DARC to Shrink Photo Resist CD	Haq	15/189295	6/22/2016	1/30/2018			
	Scanning Ferromagnetic Resonance for Wafer-Level Characteristics of Magnetic Thin Films and Multilayers	Guisan	15/463074	3/20/2017				
	Protective Passivation Layer for Magnetic Tunnel Junctions	Iwata	15/463113	3/20/2017				
US9972777	MTJ Device Process/Integration Method with Pre-Patterned Seed Layer	Haq	15/479497	4/5/2017	5/15/2018			
	Post Treatment to Reduce Shunting Devices for Physical Etching Process	Wang	15/479514	4/5/2017				
US9935281	Dielectric Encapsulation Layer for Magnetic Tunnel Junction (MTJ) Devices using Radio Frequency (RF) Sputtering	Patel	15/479522	4/5/2017	4/3/2018			
	A Method to Remove Sidewall Damage after MTJ Etching	Zhongjian	15/465642	3/22/2017				
	Combined Physical and Chemical Etch to Reduce Magnetic Tunnel Junction (MTJ) Sidewall Damage	Shen	15/595484	5/15/2017				
	SiOxNy-based Encapsulation Layer for Magnetic Tunnel Junctions	Sunder	15/619825	6/12/2017				
US1001465	Maintaining Coercive Field After High Temperature Anneal for Magnetic Device Applications with Perpendicular Magnetic Anisotropy	Liu	15/477268	4/3/2017	7/3/2018			
	Maintaining Coercive Field After High Temperature Anneal for Magnetic Device Applications with Perpendicular Magnetic Anisotropy	Liu	16/022662	6/29/2018				
US10038138	High Temperature Volatilization of Sidewall Materials from Patterned Magnetic Tunnel Junctions	Patel	15/728639	10/10/2017	7/13/2018			
US10043851	Improve Etch Selectivity by Introducing Oxidants to Noble Gas During Physical MTJ Etching	Shen	15/688113	8/3/2017	8/7/2018			
	Low Resistance MgO Capping Layer for Perpendicularly Magnetized magnetic Tunnel Junctions	Patel	15/841479	12/14/2017				
	Etch-Less Self-Aligned Magnetic Tunnel Junction (MTJ) Device Structure	Haq	15/553160	7/19/2017				
	Pulse Writing in Perpendicular Magnetic Recording	Tang	15/933486	3/23/2018				
	Electrical Testing Apparatus for Spintronics Devices	Jan	15/902407	2/22/2018				
	Improving MTJ Device Performance by Controlling Device Shape	Haq	15/810494	11/13/2017				
	Ferromagnetic Resonance (FMR) Electrical Testing Apparatus for Spintronic Devices	Jan	15/875004	1/19/2018				
US10153427	Improved Magnetic Tunnel Junction (MTJ) Performance by Introducing Oxidants to Methanol with or without Noble Gas during MTJ Etch	Shen	15/858128	12/29/2017	12/11/2018			

	Improvement of MTJ Device Performance by Adding Stress Modulation Layer to MTJ Device Structure	Haq	15/968035	5/1/2018				
US8710603	Engineered Magnetic Layer Having Improved Perpendicular Anisotropy Using Glassing Agents for Spintronics Applications	Jan	13408556	2/29/2012	4/29/2014			
US8998260	Engineered Magnetic Layer Having Improved Perpendicular Anisotropy Using Glassing Agents for Spintronics Applications	Jan	13548859	7/13/2012	4/15/2014			
US9252710	Free Layer with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	13686169	11/27/2012	2/2/2016			
US9437268	Free Layer with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	14866871	10/19/2015	9/6/2016			
US8981505	Mg Discontinuous Insertion Layer for Improving MTJ Shunt	Moriyama	13739016	1/11/2013	3/17/2015			
US9082960	Fully Compensated Synthetic Antiferromagnet for Spintronics Applications	Jan	13863542	4/16/2013	7/14/2015			
US9147333	Hybridized Oxide Capping Layer for Perpendicular Magnetic Anisotropy	Pi	13935826	7/5/2013	9/29/2015			
US9236558	Hybridized Oxide Capping Layer for Perpendicular Magnetic Anisotropy	Pi	14842038	9/1/2015	1/12/2016			
US9276201	Hybridized Oxide Capping Layer for Perpendicular Magnetic Anisotropy	Pi	14867047	9/29/2015	9/1/2016			
US9425387	Maintain Coercive Field after High Temperature Anneal for Magnetic Device Applications with Perpendicular Magnetic Anisotropy	Liu	14847433	9/8/2015	8/23/2016			
US9490054	Seed Layer for Multilayer Magnetic Materials	Jan	13549327	10/11/2012	11/8/2016			
	Improved Seed Layer for Multilayer Magnetic Materials	Jan	15344618	11/7/2016				
	Multiple Hard Mask Patterning to Fabricate 20nm and Below MRAM Devices	Yang	15790849	10/23/2017				
	Dual Magnetic Tunnel Junction Stack Design	Sundar	16133864	9/18/2018				
	Improved CD Uniformity of Island Photo Resist Pattern (Isolated) Using Alternating Phase Shifting Mask	Haq	16133869	9/18/2018				
	Self-Aligned Encapsulation Hard Mask to Separate Physically Under-Etched MTJ Cells to Reduce Conductive Re-Deposition	Yang	16113079	8/27/2018				
	Large Height Tree-Like Sub 30nm Vias to Reduce Conductive Material Re-Deposition for Sub 60nm MRAM Devices	Yang	16113088	8/27/2018				
	Highly Physical Etch Resistive Photoresist Mask to Define Large Height Sub 30nm Via and Metal Hard Mask for MRAM Devices	Yang	16133855	9/18/2018				
	Dual Magnetic Tunnel Junction Devices for Magnetic Random Access Memory (MRAM)	Sundar	16056791	8/7/2018				
	Multi-Probe Ferromagnetic Resonance (FMR) Apparatus for Wafer Level Characterization of Magnetic Films	Guisan	16056783	8/7/2018				
	Improved Magnetic Layer for Magnetic Random Access Memory (MRAM) by Moment Enhancement	Jan	16109083	8/22/2018				
	Avoiding Oxygen Plasma Damage During Hard Mask Etching in Magnetic Tunnel Junction (MTJ) Fabrication Process	Shen	16/056770	8/7/2018				
	Method for Measuring Saturation Magnetization of Magnetic Films and Multilayer Stacks	Guisan	16/161166	10/16/2018				
	Monolayer-by-Monolayer Growth of MgO Layers Using Mg Sublimation and Oxidation	Patel	16161161	10/16/2018				
	Multiple Spacer Assisted Physical Etching of Sub 60nm MRAM Devices	Yang	16161139	10/16/2018				
	Multi-layer Structure for Reducing Film Roughness in Magnetic Devices	Zhu	16173201	10/29/2018				
	Cooling for PMA (Perpendicular Magnetic Anisotropy) Enhancement of STT-MRAM (Spin-Torque Transfer-Magnetic Random Access Memory) Devices	Liu	16184528	11/8/2018				
US6950480	Method of Forming a Magnetic Tunneling Junction (MTJ) MRAM Device and a TMR Read Head	Hong	10848310	5/19/2004	11/1/2005			
US7238979	Method of Forming a Magnetic Tunneling Junction (MTJ) MRAM	Hong	11238049	5/19/2004	7/3/2007			
US8803293	Method to Reduce Magnetic Film Stress for Better Yield	Zhong	13488258	5/11/2012	8/12/2014			

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US8933542	Method to Reduce Magnetic Film Stress for Better Yield	Zhong	14454324	8/7/2014	1/13/2015			
	Seed Layer for PMA Thin Film	Moriyama	13863545	4/16/2013				
	Reduction of Barrier Resistance X Area (RA) Product and Protection of (PMA) for Magnetic Device Applications	Liu	14278243	5/15/2014				
US9987350	MTJ Etching with Improved Uniformity and Profile by Adding Passivation Step	Shen	14726545	5/31/2015	2/6/2018			
US9842988	Magnetic Tunnel Junction with Low Defect Rate after High Temperature Anneal for Magnetic Device Applications	Liu	14803111	7/20/2015	12/12/2017			
	Magnetic Tunnel Junction with Low Defect Rate after High Temperature Anneal for Magnetic Device Applications	Liu	15835592	12/8/2017				
	Physical Cleaning with in-Situ Dielectric Encapsulation Layer for Spintronic Device Application	Wang	14813854	7/30/2015				
	Title Multilayer Structure for Reducing Film Roughness in Magnetic Devices	Zhu	16221868	12/17/2018				HT15-008_CIPB_CON Contin of s/n 16173201
	Minimal Thickness Synthetic Antiferromagnetic (SAF) Structure with Perpendicular Magnetic Anisotropy for STT-MRAM	Beach	16258770	1/28/2019				HT12-011BB Div of s/n 14489507

	A	B	C	D	E	F	G	H
1	Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	IBM	Renesas
2	4936862	Reference Cell Scheme for MRAM	Yang	2006-314888	11/21/2006	3/2/2012	○	○
3	5305584	Spacer Structure in MRAM Cell And Method Of Fabricating The Same	Yuan	2006-323676	11/30/2006	7/5/2013	○	○
4	5357367	A Configurable MRAM	Yang	2006-342730	12/20/2006	9/6/2013	○	○
5	5066989	A Novel Oxidation Structure/Method To Form MgO/NiFe(free layer)-MTJ for high performance MRAM appli	Hong	2006-346048	12/22/2006	8/24/2012	○	○
6	5066034	A Novel Method To Form Non-magnetic NiFeMg Cap for the NiFe(free)-MTJ Stack to Enhance dR/R	Hong	2007-106461	4/13/2007	8/24/2012	○	○
7	5346453	Paramagnetic-NiFeHf Capping Layer Is Deposited By Co-Sputtering of NiFe and Hf	Hong	2007-199432	7/31/2007	8/23/2013	○	○
8	5006154	Barium Doped Cap and Free Layer for MRAM Device	Hong	2007-270566	10/17/2007	8/1/2012	○	○
9	5582526	Spin Transfer MRAM Device With Novel Magnetic Synthetic Free Layer	Guo	2008-80560	3/26/2008	8/20/2014	○	○
10	5317524	Spin Torque Switching MRAM, SpinRAM, Array	Yang	2008-114686	4/24/2008	7/19/2013	○	○
11	5451977	A Novel SyAF Structure To Fabricate Mbit MTJ MRAM	Hong	2008-50230	3/10/2008	1/15/2014	○	○
12	5279384	A High Performance MTJ Element for STT-RAM And Method For Making the Same	Hong	2008-190225	7/23/2008	5/31/2013	○	○
13	5537791	Method Of Magnetic Tunneling Layer Processes For Spin-Transfer Torque MRAM Devices	Zhong	2008-266948	10/17/2008	5/8/2014	○	○
14	5460906	Spin Transfer MRAM Device with Separated CPP Assisted Writing	Guo	2010-534834	5/21/2010	1/24/2014	○	○
15	5433284	A Low Switching Current MTJ Element For Ultra-High STT-RAM and Method For Making The Same	Hong	2009-85227	4/9/2009	12/13/2013	○	○
16	5571096	Boosted Gate Voltage Programming for Spin-RAM Array	Hsu	2011-537409	6/20/2011	7/4/2014	○	
17	5470179	Gate Drive Voltage Boost Schemes For Memory Array	Yang	2010-154347	7/6/2010	2/7/2014	○	○
18	5771370	STT-RAM with A Magnetic Tunnel Junction Written In Thermally Assisted Method	Hong	2010-163362	7/20/2010	7/3/2015	○	○
19	5674819	A Read Disturb Free SMT MRAM Reference Cell Circuit	Yang	2012-551977	8/5/2012	1/9/2015	○	○
20	5735661	Magnetic Element with Improved Out-of-Plane Anisotropy for Spintronic Applications	Jen	2013-553563	9/8/2013	4/24/2015	○	
21	5674744	MAGNETIC MEMORY STRUCTURE AND TUNNEL MAGNETORESISTANCE EFFECT REPRODUCTION HEAD AND MANUFACTURING METHOD THEREFOR	Hong	2012-232207	10/19/2012	1/9/2015	○	○
22	4563160	MRAM Cell With Flat Topography and Controlled Bit Line to Free Layer Distance and Method of Manufact	Han	2004-357266	12/9/2004	8/6/2010	○	○
23	5377547	A Novel Buffer (Seed) Layer for Making a High-Performance Magnetic Tunneling Junction MRAM	Hong	2011-041736	2/28/2011	10/4/2013		
24	5178788	Adaptive Algorithm for MRAM Manufacturing	Yang	2010-169760	7/29/2010	1/18/2013	○	○
25	5179787	Adaptive Algorithm for MRAM Manufacturing	Yang	2010-169759	7/28/2010	1/19/2013	○	○
26	5153061	A Novel Underlayer For High Performance Magnetic Tunneling Junction MRAM	Hong	2005-192226	6/30/2005	12/14/2012	○	○
27	5038317	Method of Fabricating MRAM Cell Structure Containing Sidewall Spacers	Yang	2006-112650	4/14/2006	7/13/2012	○	○

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1	Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	IBM	Renesas
2	1793433	Spacer Structure in MRAM Cell And Method Of Fabricating The Same	Yuan	08392015.1	2009/11/7	2013/1/15	○	○
3	EP1801810	A Configurable MRAM	Yang	08392018.5	2006/12/20	2010/5/19	○	○
4		A Novel Oxidation Structure/Method To Form MgO/NiFe(free layer)-MTJ for high performance MRAM appli	Hong	08392019.3	2008/12/20		○	○
5	EP1885056	Paramagnetic-NiFeHf Capping Layer Is Deposited By Co-Sputtering of NiFe and Hf	Hong	07392004.3	2007/7/30	2009/12/9	○	○
6	EP1818147	Hafnium Doped Cap and Free Layer for MRAM Device	Hong	07392007.6	2007/9/27	2017/12/13	○	○
7		MRAM with Enhanced Programming Margin	Min	08392002.5	2008/3/27		○	○
8	EP1988196	Spin Torque Switching MRAM, SpinRAM, Array	Yang	08392003.3	2008/3/27	2012/6/17	○	○
9	EP1968130	A Novel SyAF Structure To Fabricate Mini MTJ MRAM	Hong	08398008.2	2008/3/7	2013/10/2	○	○
10	EP2073285	A High Performance MTJ Element for STT-RAM And Method For Making the Same	Hong	08392010.8	2008/7/9	2015/4/29	○	○
11		Boosted Gate Voltage Programming for Spin-RAM Array	Hsu	08827846.6	2009/10/19		○	○
12		Gate Drive Voltage Boost Schemes for Memory Array II	Yang	10810283.3	2010/7/2		○	○
13		Method and Apparatus for Scrubbing Accumulated Data Errors from a Memory System	Yang	10792437.5	2011/12/26		○	○
14	EP2377126	A Novel Free Layer/Capping Layer for High Performance MRAM MTJ	Hong	10731920.4	2011/7/5	2017/9/27	○	○
15	EP2412003	METHOD OF DOUBLE PATTERNING AND ETCHING MAGNETIC TUNNEL JUNCTION STRUCTURES FOR SPIN-TRANSFER TORQUE MRAM DEVICES	Belen	10756454.4	2011/10/24	2017/10/18	○	○
16		Shared Bit Line SMT MRAM Array with Shunting Transistors Between the Bit Lines	Yang	11803933.8	2011/6/28		○	○
17		A Read Disturb Free SMT MRAM Reference Cell Circuit	Yang	11740139.6	2012/7/28		○	○
18		A Novel Bit Line Preparation Method in MRAM Fabrication	Guomin	10825330.3	2012/5/20		○	○
19		Replaceable, Precise-Tracking Reference Lines	Pu	11827099.0	2013/4/22		○	○
20		Reference Cell Architectures for Small Memory Array Block Activation	Suanga	11834756.6	2013/5/21		○	
21		Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	13748182	2012/7/30			
22		Co/Ni Multilayers with Improved Out-of-Plane Anisotropy for Magnetic Device Applications	Jan	13748182.6	2013/7/30		○	
23		Magnetic Element with Improved Out-of-Plane Anisotropy for Spintronic Applications	Jan	12744881.9	2012/2/10		○	
24	EP2705518	Multilayers Having Reduced Perpendicular Demagnetizing Field using Moment Dilution for Spintronic Applications	Jan	12779816	2012/4/28	2017/4/19	○	
25	EP2898044	Storage Element for STT MRAM Applications	Kula	13796212	2013/9/13	2018/1/10	○	○
26		Storage Element for STT MRAM Applications	Kula	19150684.1	2018/1/9		○	○
27	EP2820681	High Thermal Stability Reference Structure with Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	13754577	2013/1/24	2017/12/20		
28	EP2834916	Reduction of Capping Layer Resistance Area Product for Magnetic Device Applications	Jan	13772601.4	2013/3/27	2017/11/15		
29	EP2820649	High Thermal Stability Free Layer with High Out-of-Plane Anisotropy for Magnetic Device Applications	Wang	13755666	2013/2/27	2017/11/15		
30	2839501	Free Layer with High Thermal Stability for Magnetic Device Applications by Insertion of a Boron Doping Layer	Wang	13777520.4	2013/4/17	2016/12/21		
31	EP1624458	Adaptive Algorithm for MRAM Manufacturing	Yang	05392005.4	2005/8/14	2013/4/23	○	○
32	EP1615226	A Novel Underlayer For High Performance Magnetic Tunneling Junction MRAM	Hong	05392007.0	2005/8/14	2012/11/14	○	○

	A	B	C	D	E	F	G	H
1	Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	IBM	Renesas
33	EP1607990	A Novel Capping Structure for Enhancing dR/R of the MTJ Device	Hong	05392006.2	2005/6/14	2010/2/24	○	○
34		MTJ Incorporating CoFe/N Multilayer Film with Perpendicular Magnetic Anisotropy for MRAM Application	Zhang	10827271	2010/10/26		○	○
35		Improved Seed Layer for Multilayer Magnetic Materials	Jan	13783498.2	2012/10/11			
36		An Adaptive Reference Scheme for Magnetic Memory Applications	Jan	13786114.2	2013/10/23			
37		Implementation of One Time Programmable Memory using a MRAM Stack Design	Jan	16715700.7	2016/3/22			
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39								

	A	B	C	D	E	F	G	H
1	Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	IBM	Renesas
2	741300	Magnetic Random Access Memory Array with Coupled Soft Adjacent Magnetic Layer	Gua	10-2005-0053660	6/21/2005	7/13/2007	○	○
3	10-1143337	Adaptive Algorithms for MRAM Manufacturing	Yang	10-2005-0063471	7/13/2005	4/30/2012	○	○
4	10-1204669	Adaptive Algorithms for MRAM Manufacturing	Yang	10-2011-0140587	12/22/2011	11/20/2012	○	○
5	10-1165356	A Novel Underlayer For High Performance Magnetic Tunneling Junction MRAM	Hong	10-2005-0058088	6/30/2005	7/11/2012	○	○
6	10-1365476	Adaptive Algorithms for MRAM Manufacturing	Yang	10-2011-0140582	12/22/2011	2/14/2014	○	○

China

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1	Issued Patent Number	Title	First Inventor	Serial Number	File Date	Issue Date	Status
2	2849742	Improved Seed Layer for Multilayer Magnetic Materials	Jan	201380061488.2	2015/5/28	2018/3/20	Issued
3		Implementation of One Time Programmable Memory using a MRAM Stack Design	Jan	201680052700.2	2017/11/15		Pending

Headway Docket Number	Attorney Ref. Number	Title	First Inventor	Assignee	Priority Date	Serial Number	File Date	Issued Patent Number	Issue Date	Status
HT17-006		STT-MRAM HEAT SINK AND MAGNETIC SHIELD STRUCTURE DESIGN FOR MORE ROBUST READ/WRITE PERFORMANCE		Headway	29-Dec-17	107147487	28-Dec-18			
HT17-025		FERROMAGNETIC RESONANCE (FMR) ELECTRICAL TESTING APPARATUS FOR SPINTRONIC DEVICES	Jin	Headway	19-Jan-18	108101891	17-Jan-19			
HT17-037		NITRIDE CAPPING LAYER FOR SPIN TORQUE TRANSFER (STT)-MAGNETORESISTIVE RANDOM ACCESS MEMORY (MRAM)	Iwata	Headway	26-Jan-18	108102292	23-Jan-19			

PCT Applications not yet at National Stage						
	Title	Inventor	Appl No	Filing Date	Docket Number	National Stage Deadline (30 mo)
	MgO Insertion into Free Layer for Magnetic Memory Applications	Iwata	PCT/US2018/019841	2/27/2018	HT2016025PCT	9/17/2019
	Protective Passivation Layer for Magnetic Tunnel Junctions	Iwata	PCT/US2018/020075	2/28/2018	HT2016014PCT	9/20/2019
	Scanning Ferromagnetic Resonance (FMR) for Wafer-Level Characterization of Magnetic Films and Multilayers	Guisan	PCT/US2018/020381	3/1/2018	HT2016012PCT	9/20/2019
	Spacer Assisted Ion Beam Etching of Spin Torque Magnetic Random Access Memory	Yang	PCT/US2018/020594	3/2/2018	HT2017007PCT	9/22/2019
	Method to Remove Sidewall Damage after MTJ Etching	Teng	PCT/US2018/020854	3/5/2018	HT2017004PCT	9/22/2019
	Maintaining Coercive Field after High Temperature Anneal for Magnetic Device Applications with Perpendicular Magnetic Anisot	Liu	PCT/US2018/021007	3/6/2018	HT2017009PCT	10/3/2019
	MTJ Device Process/Integration Method with Pre-Patterned Seed Layer	Haq	PCT/US2018/021286	3/7/2018	HT2017001PCT	10/5/2019
	Dielectric Encapsulation Layer for Magnetic Tunnel Junction (MTJ) Devices Using Radio Frequency (RF) Sputtering	Patel	PCT/US2018/021248	3/7/2018	HT2017003PCT	10/5/2019
	Post Treatment to Reduce Shunting Devices for Physical Etching Process	Wang	PCT/US2018/021452	3/8/2018	HT2017002PCT	10/5/2019
	Combined Physical and Chemical Etch to Reduce Magnetic Tunnel Junction (MTJ) Sidewall Damage	Shen	PCT/US2018/032196	5/11/2018	HT2017005PCT	11/15/2019
	Multilayer Structure for Reducing Film Roughness in Magnetic Devices	Zhu	PCT/US2018/032637	5/15/2018	HT2015006CIP_PCT	11/19/2019
	Etch-Less Self-Aligned Magnetic Tunnel Junction (MTJ) Device Structure	Haq	PCT/US2018/035101	5/30/2018	HT2017015PCT	1/18/2020
	Silicon Oxynitride Based Encapsulation Layer for Magnetic Tunnel Junctions	Sundar	PCT/US2018/035097	5/30/2018	HT2017008PCT	12/12/2019
	High Thermal Stability by Doping of Oxide Capping Layer for Spin Torque Transfer (STT) Magnetic Random Access Memory (MRAM) A	Jan	PCT/US2018/055043	10/9/2018	HT2017034PCT	4/10/2020
	High Temperature Volatilization of Sidewall Materials from Patterned Magnetic Tunnel Junctions	Patel	PCT/US2018/055042	10/9/2018	HT2017010PCT	4/10/2020
	Multiple Hard Mask Patterning to Fabricate 20NM and Below MRAM Devices	Yang	PCT/US2018/056480	10/19/2018	HT2017027PCT	4/23/2020
	Free Layer Sidewall Oxidation and Spacer Assisted Magnetic Tunnel Junction (MTJ) Etch for High Performance Magnetoresistive R	Yang	PCT/US2018/056447	10/19/2018	HT2017036PCT	4/20/2020
	Initialization Process for Magnetic Random Access Memory (MRAM) Production	Lee	PCT/US2018/059803	11/9/2018	HT2017022PCT	5/20/2020
	Improving MTJ Device Performance by Controlling Device Shape	Haq	PCT/US2018/059802	11/8/2018	HT2017023PCT	5/13/2020
	Low Resistance MgO Capping Layer for Perpendicularly Magnetized Magnetic Tunnel Junctions	Patel	PCT/US18/064425	12/7/2018	HT2017014PCT	6/14/2020
	Improved Magnetic Tunnel Junction (MTJ) Performance by introducing Oxidants to Methanol with or without Noble Gas During MTJ	Shen	PCT/US2018/064423	12/7/2018	HT2017051PCT	6/28/2020
	STT-MRAM Heat Sink and Magnetic Shield Structure Design for More Robust Read/Write Performance	Zhong	PCT/US2018/067951	12/28/2018	HT2017008PCT	6/29/2020
	Ferromagnetic Resonance (FMR) Electrical Testing Apparatus for Spintronic Devices	Jan	PCT/US2019/013963	1/17/2019	HT2017025PCT	7/15/2020
	Nitride Capping Layer for Spin Torque Transfer (STT)-Magnetoresistive Random Access Memory (MRAM)	Iwata	PCT/US2019/015129	1/25/2019	HT2017037PCT	7/26/2020